



6-CHANNEL, FERRITE HEAD READ/WRITE PREAMPLIFIER

July, 1991

**THREE-TERMINAL
READ/WRITE PREAMPS**

- Enhanced System Write to Read Recovery Time
- Power-Up/Power-Down Write Protection
- Plug Compatible to the VTC VM117
- Operates on +5V and +12V Power Supplies
- Write-Unsafe Detection Circuitry
- Programmable Write-Current Source
- TTL-Compatible Control Lines
- Low Input Noise of 1.4nV/√Hz maximum
- For Use With Center-Tapped Ferrite Heads
- Optional Internal Head Damping Resistors
- Available in 2, 4, or 6 Channels
- Mirror Image Pinout Option Available

The VM310/VM310R is a bipolar, monolithic read/write preamp circuit, designed for use with center-tapped ferrite recording heads. The circuit provides a low-noise read data path for signals from the disk in the read mode and provides write-current control for data written on the disk in the write mode.

The block diagram illustrates the internal architecture of the 64K16B16 DRAM. It features a central core labeled "Write Current Switches" and "Differential Read Amplifiers". The core is connected to various control and data lines. On the left, control inputs include R/WC, CS, RDY, and RDY. On the right, data outputs are labeled H0X, H0Y, H1X, H1Y, H2X, H2Y, H3X, H3Y, H4X, H4Y, H5X, and H5Y. At the top, power and status inputs are WUS, VDD2, and VCT. At the bottom, control inputs include WC, HS0, HS1, HS2, VDD1, VCC, and GND. The architecture includes a "Mode Select" block, a "Write Unsafe Detector", a "Center Tap Driver", a "Read Buffer", a "Read Preamp", a "WDFB" (Write Data Feedback) block, a "Write Driver", a "Write Current Source", and a "Decoder". The "Write Current Source" and "Decoder" are connected to the bottom control lines. The "Read Buffer" and "Read Preamp" are connected to the data outputs. The "Write Driver" and "WDFB" are connected to the data inputs. The "Mode Select" block is connected to the top control lines. The "Write Unsafe Detector" and "Center Tap Driver" are connected to the top control lines. The "Write Current Switches" and "Differential Read Amplifiers" are the central components of the array.

2-Channel 20-lead SOIC

CS	1	20	HS0
GND	2	19	WDI
NC	3	18	VDD1
NC	4	17	VDD2
H0X	5	16	VCT
H0Y	6	15	H1X
NC	7	14	H1Y
R/W	8	13	WUS
WC	9	12	VCC
RDX	10	11	RDY

4-Channel 24-lead SOIC

CS	1	24	HS0
GND	2	23	HS1
H0X	3	22	WDI
H0Y	4	21	VDD1
H1X	5	20	VDD2
H1Y	6	19	VCT
H2X	7	18	H3X
H2Y	8	17	H3Y
R/W	9	16	NC
WC	10	15	NC
RDX	11	14	WUS
RDY	12	13	VCC

4-Channel 22-lead P-DIP

CS	1	22	HS0
GND	2	21	HS1
H0X	3	20	WDI
H0Y	4	19	VDD1
H1X	5	18	VDD2
H1Y	6	17	VCT
H2X	7	16	H3X
H2Y	8	15	H3Y
R/W	9	14	WUS
WC	10	13	VCC
RDX	11	12	RDY

6-Channel 28-lead PLCC

HS0	1	28	HS1
CS	2	27	HS2
GND	3	26	WDI
H0X	4	25	VDD1
H0Y	5	24	VDD2
H1X	6	23	VCT
H1Y	7	22	HSX
H2X	8	21	HSY
H2Y	9	20	H4X
R/W	10	19	H4Y
WC	11	18	H3X
NC	12	17	H3Y
RDX	13	16	WUS
RDY	14	15	VCC

ABSOLUTE MAXIMUM RATINGS**Power Supply Voltages:**

VDD1	-0.3V to 14V
VDD2	-0.3V to 14V
VCC	-0.3V to 6V

Pin Voltages:

Head Select (HS)	-0.3V to VCC + 0.3V
Write Unsafe (WUS)	-0.3V to VCC + 0.3V
Write Data Input (WDI)	-0.3V to VCC + 0.3V
Read/Write Select (R/W)	-0.3V to VCC + 0.3V

Output Current:

Write Current (Iw)	60mA
Read Data (RDX, RDY)	10mA
Center Tap Current (ICT)	60mA
Write Unsafe (WUS)	12mA

Operating Temperature Range

Storage Temperature Range

Lead Temperature (Soldering 60 Sec.)

Junction Temperature

Thermal Characteristics,

20-lead SOIC	65°C/W
24-lead SOIC	80°C/W
24-lead P-DIP	65°C/W
28-lead SOIC	70°C/W
28-lead PLCC	65°C/W

RECOMMENDED OPERATING CONDITIONS**DC Power Supply Voltage:**

VDD1	12V ± 10%
VDD2	7.0V to VDD1
VCC	5V ± 10%

Head Inductance (L_H)Damping Resistance (R_D) (Note 1)R_{CT} Resistor (Note 2)

RDX, RDY Output Current (Read Mode)

Write Current

Junction Temperature

Note 1: VM310/VM310R has head damping resistors placed on the chip; the standard value is 750Ω ± 20%.

Note 2: Resistor (R_{CT}) used to limit power dissipation.

CIRCUIT OPERATION

The VM310 addresses up to six center-tapped ferrite heads and operates as a write-current switch in the write mode and as a low-noise differential amplifier in the read mode. Head selection is controlled by HS0, HS1 and HS2 lines and mode select is controlled by the CS and R/W select lines as shown in Tables 1 and 2. Both CS and R/W have internal pull-up resistors to prevent accidental write condition. Unsafe conditions are indicated by the WUS line.

Write Mode

In the write mode, the VM310 operates as a write-current switch. Write current is supplied by an internal current source. The magnitude of the write current is determined by an external resistor connected between WC and ground. The head current is switched between the X and Y side of a selected head by falling transitions on WDI (write data input). When switching to the write mode from the read mode, the write data flip-flop is initialized to pass head current through the X side of the head.

The write unsafe (WUS), open collector output, will give a high level for any of the following unsafe conditions:

- Open Head
- No Write Current
- Read Mode
- Idle Mode
- Write Data Frequency Too Low
- Head Center-Tap Open

After the fault condition is corrected, it takes two negative transitions on WDI to clear the WUS line. To further protect accidental writing to the disk, a voltage fault detection circuit ensures no write current during power loss or power sequencing. An enhanced write to read recovery time is achieved by maintaining a constant common mode level on the RDX, RDY outputs between write and read modes.

Write mode power dissipation may be minimized by connecting a resistor (R_{CT}) between VDD2 and VDD1. The optimum value for R_{CT} is 120x40/Iw (Iw in mA). At write currents below 15mA, the read mode dissipation is higher than write mode and need not be used. In this case VDD2 is connected to VDD1.

Read Mode

In the read mode the circuit operates as a low-noise differential amplifier. The write-current source is turned off and the write-data flip-flop is set. The selected head provides a differential input. The RDX and RDY pins provide differential emitter follower outputs which are in phase with the X and Y inputs and should be AC coupled to the load. Write current is deactivated for both the read and idle mode so that external gating is not required.

Idle Mode

In the idle mode (\overline{CS} = high level) both the read amp and write driver are disabled and the devices power dissipation is minimal. The internal write current reference is disabled and the RDX, RDY outputs are in a high impedance state. Hence, for multiply chip usage. The RDX, RDY outputs maybe wire OR'ed, and a common write current resistor (RWC) may be used to set the write current.

- Read-to-Write Recovery should be enhanced when doing a DC erase. Layout of the chip minimizes thermal effects on the read amp for improved write-to-read recovery.
- The write unsafe circuit has a much larger inductance range and is not dependent on the magnitude of Iw. This part will serve a wider range of head loads and write current values.

PIN DESCRIPTIONS

NAME	I/O	DESCRIPTION
HS0-HS2	I	Head Select Inputs
CS	I	Chip Select: a low level enables device
RW	I	Read/Write: a high level selects read mode
WUS	O*	Write Unsafe: a high level indicates an unsafe writing condition
WDI	I	Write Data In: negative edge toggles the head current
H0X-H5X H0Y-H5Y	I/O	X,Y head connections
RDX, RDY	O*	X,Y Read Data: diff. read signal outputs
WC		Write Current: used to set the magnitude of the write current
VCT		Voltage Center Tap: voltage source for head center tap
VCC		+5 V
VDD1		+12 V
VDD2		Positive power supply for the center tap voltage source
GND		Ground

* For multiple chip usage, these signals can be wire OR'ed

Table 1: Head Select

HS0	HS1	HS2	HEAD
L	L	L	0
H	L	L	1
L	H	L	2
H	H	L	3
L	L	H	4
H	L	H	5
X	H	H	None

Table 2: Mode Select

CS	R/W	MODE
L	L	Write
L	H	Read
H	X	Idle

Table 3: External Resistor vs. Write Current

External resistor vs. DC write current I_W into the selected head terminal X or Y with V_{CT} shorted only to the respective X or Y terminal.	
External Resistor $R_{WC} (\Omega)$	Write Current $I_W (mA)$
249	10
124	20
82.5	30
61.9	40

Note: Effective current I_{FLUX} generated in the magnetic head is related to I_W by the expression:

$$I_{FLUX} = I_W \left(\frac{R_D}{R_H + R_D} \right)$$

Where R_H equals the full coil resistance of a center-tapped ferrite head and R_D is the damping resistor connected internally or externally between the X and Y terminals. Nominal internal resistance on VM310R is 750Ω.

THREE-TERMINAL
READ/WRITE PREAMPS

DC CHARACTERISTICS

Unless otherwise specified, $V_{DD1} = 12V \pm 10\%$, $V_{CC1} = V_{CC2} = 5V \pm 10\%$, $T_A = 25^\circ C$.

PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
POWER SUPPLY						
Positive Supply Current	I _{DD}	Read Mode		19	25	mA
		Write Mode		9 + I _W	12 + I _W	
		Idle Mode		9	12	
	I _{CC}	Read Mode		11	15	mA
		Write Mode		13	18	
Positive Supply Current	I _{CC}	Idle Mode		9	12	mA
Power Supply Dissipation T _A = 70°C	P _D	Idle Mode			200	mW
		Read Mode			425	
		Write Mode I _W = 40mA, R _{CT} = 120Ω			500	
		Write Mode I _W = 40mA, R _{CT} = 0Ω			675	
DIGITAL TTL INPUTS: CS, R/W, HS, WDI						
Input High Voltage	V _{IH}		2		V _{CC} + 0.3	V
Input Low Voltage	V _{IL}		-0.3		0.8	V
Input High Current	I _{IH}	V _{IH} = 2.0V, V _{CC} = 5.5V	-400		100	μA
Input Low Current	I _{IL}	V _{IL} = 0.4V, V _{CC} = 5.5V	-0.4			mA
WUS OUTPUT						
Low Voltage	V _{OL}	I _{OL} = 8 mA (Safe)			0.5	V
High Current	I _{OH}	V _{OH} = 5V (Unsafe)			100	μA
HEAD CENTER TAP VOLTAGES						
Read Mode	V _{CT}	Read Mode		4.2		V
Write Mode	V _{CT}	Write Mode		6.6		V

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READ/WRITE PREAMPS

VM310/VM310R

READ CHARACTERISTICS Unless otherwise specified, $I_W = 40\text{mA}$, $L_H = 2.5\mu\text{H}$, $R_D = 750\Omega$, $f_{\text{DATA}} = 5\text{MHz}$, $C_L (\text{RDX, RDY}) \leq 20\text{pF}$, $T_A = 25^\circ\text{C}$.

PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
Differential Voltage Gain	A_V	$V_{IN} = 1\text{mVrms}$, $f = 500\text{KHz}$ $R_L (\text{RDX, RDY}) = 1\text{K}\Omega$	85		115	V/V
Dynamic Range	DR	DC input voltage where AC gain falls 10%, $V_{IN} = V_{DC} + 0.5\text{mVp-p}$ $f = 500\text{KHz}$	-3		3	mV
Bandwidth (-3dB)	BW	$V_{IN} = 1\text{mVp-p}$, $Z_S < 5\Omega$	30			MHz
Input Noise Voltage	e_{in}	$L_H = 0$, $R_H = 0$, $BW = 15\text{MHz}$		1.2	1.4	nV/ $\sqrt{\text{Hz}}$
Differential Input Capacitance	C_{IN}	$f = 5\text{MHz}$			20	pF
Differential Input Resistance	R_{IN}	VM310, $f = 5\text{MHz}$	2			K Ω
		VM310R, $f = 5\text{MHz}$	460		860	Ω
Input Current (per side)	I_{IN}				80	μA
Common Mode Rejection Ratio	CMRR	$V_{CM} = V_{CT} + 100\text{mVp-p}$, $f = 5\text{MHz}$	50			dB
Power Supply Rejection Ratio	PSRR	V_{DD} or $V_{CC} = 100\text{mVp-p}$, $f = 5\text{MHz}$	45			dB
Channel Separation	CS	$V_{IN} = 100\text{mVp-p}$, $f = 5\text{MHz}$ Three channel driven, selected channel measured	45			dB
Output Offset Voltage	V_{OS}		-200		200	mV
Common Mode Output Voltage	V_{OCM}		4.5		6.5	V
Head Center Tap Voltage	V_{CT}	Read Mode		4.2		V
Single-Ended Output Resistance	R_{SEO}				30	Ω
Output Current	I_{OUT}	AC coupled load, RDX, RDY	2.1			mA
Head Current (per side)	I_H	Read or Idle Mode $0\text{V} \leq V_{CC} \leq 5.5\text{V}$ $0 \leq V_{DD1} \leq 13.2\text{V}$	-200		200	μA

WRITE CHARACTERISTICS Unless otherwise specified, $I_W = 40\text{mA}$, $L_H = 2.5\mu\text{H}$, $R_D = 750\Omega$, $f_{\text{DATA}} = 5\text{MHz}$,
 C_L (RDX, RDY) $\leq 20\text{pF}$, $T_A = 25^\circ\text{C}$.

PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
Write Current Range	I_W	(See table 3)	10		40	mA
Write Current Tolerance	ΔI_W	Over I_N range	-5		+5	%
Differential Head Voltage	V_{DH}		7			Vp-p
Current Gain	A_I			.99		mA/mA
Unselected Head Current	I_{UH}				2	mA p-p
Head Current Propagation Delay	t_{PD}	$L_H = 0\mu\text{H}$, $R_H = 0$, 50% WDI to 50% I_W			30	ns
Rise/Fall Time	t_r, t_f	$L_H = 0\mu\text{H}$, $R_H = 0$, 10% to 90%	5		20	ns
Symmetry	S	$[(t_r - t_f)/2]$			2	ns
Differential Output Resistance	R_{OUT}	VM310 only	10			$K\Omega$
		VM310R	600		960	Ω
Differential Output Capacitance	C_{OUT}	$f = 5\text{MHz}$			15	pF
WDI Transition Frequency	f_{min}	WUS = low	250			KHz
Center Tap Voltage	V_{CT}	Write Mode		6.6		V
Head Current (per side)	I_H	Write Mode; $0 \leq V_{CC} \leq 3.7\text{V}$; $0 \leq V_{DD1} \leq 8.7\text{V}$	-200		200	μA
RDX,RDY Output Offset Voltage	V_{OS}	Write or Idle Mode	-20		20	mV
RDX, RDY Common Mode Output Voltage	V_{CM}	Write or Idle Mode		5.3		V
RDX, RDY Leakage	I_L	RDX, RDY = 6V, Write or Idle Mode	-100		100	μA
Unselected Leakage Current	I_{UH}				85	μA

SWITCHING CHARACTERISTICS

Unless otherwise specified, $I_W = 40\text{mA}$, $L_H = 2.5\mu\text{H}$, $R_D = 750\Omega$, $f_{\text{DATA}} = 5\text{MHz}$, $C_L (\text{RDX}, \text{RDY}) \leq 20\text{pF}$, $T_A = 25^\circ\text{C}$.

PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
Read-to-Write Switching Delay	t_{RW}	50% of $\overline{\text{R/W}}$ to 90% of write output envelope			1	μs
Write-to-Read Switching Delay	t_{WR}	50% of $\overline{\text{R/W}}$ to 90% of 100mVp-p RDX, RDY envelope			1	μs
Idle-to-Write Switching Delay	t_{IW}	50% of $\overline{\text{CS}}$ to 90% of write output envelope			1	μs
Idle-to-Read Switching Delay	t_{IR}	50% of $\overline{\text{CS}}$ to 90% of 100mVp-p RDX, RDY envelope			1	μs
Write-to-Idle Switching Delay	t_{WI}	50% of $\overline{\text{CS}}$ to 10% of write output envelope			1	μs
Read-to-Idle Switching Delay	t_{RI}	50% of $\overline{\text{CS}}$ to 10% of RDX, RDY envelope			1	μs
Head Select Switching Delay	t_{HS}	50% of HS transition to 90% of 100mVp-p RDX, RDY envelope from selected head			1	μs
Write Unsafe Delay Safe to Unsafe	t_{D1}	Gate WDI. Measure from 50% of last data pulse to 50% WUS, $I_W = 10$ to 40mA	1.6		8	μs
Write Unsafe Delay Unsafe to Safe	t_{D2}	Gate WDI. Measure from 50% of falling edge of first data pulse to 50% WUS, $I_W = 10\text{mA}$			1	μs

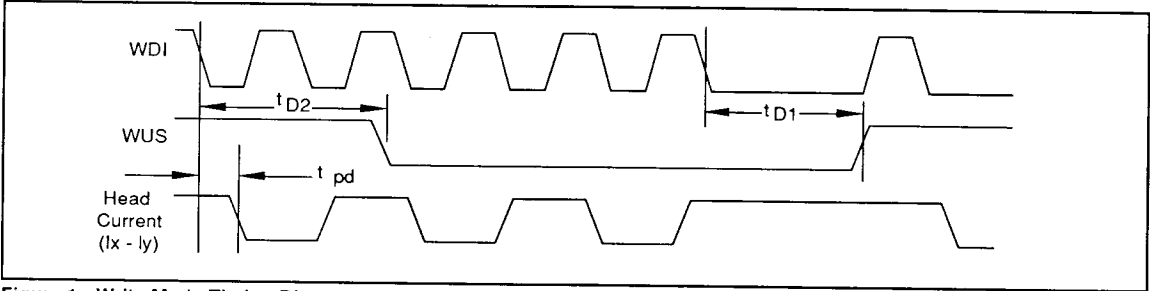


Figure 1: Write Mode Timing Diagram